

Atty. Docket No. CPAC 1017-7
Appl. No. 10/632,550

MAR 25 2005

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Marcos KARNEZOS

Examiner: Mai Huong C. Tran

Application No.: 10/632,550

Group Art Unit: 2818

Filed: August 2, 2003

Date: March 25, 2005

Title: Semiconductor multi-package module including stacked-die package and having wire bond interconnect between stacked packages

CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this correspondence is being sent by facsimile to:
Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, at the
Central Fax No. 703/872-9306 on March 25, 2005.

Signed

Bill Kennedy

MAIL STOP AMENDMENT
COMMISSIONER FOR PATENTS
P.O. Box 1450
ALEXANDRIA, VA 22313-1450

AMENDMENT

Dear Sir:

In response to the Office action mailed October 7, 2004, kindly amend the application as follows.

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the **Listing of Claims** which begins on page 4 of this paper.

Remarks begin on page 6 of this paper.